



STPS10L40CT/CG/CF

LOW DROP POWER SCHOTTKY RECTIFIER

MAJOR PRODUCTS CHARACTERISTICS

I _{F(AV)}	2x5 A
V _{RRM}	40 V
T _{j(max)}	150°C
V _{F(max)}	0.46 V

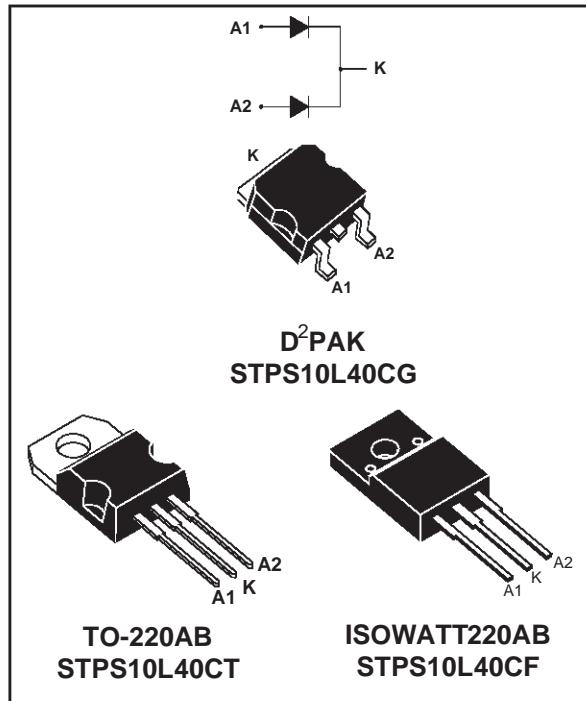
FEATURES AND BENEFITS

- LOW FORWARD VOLTAGE DROP MEANING VERY SMALL CONDUCTION LOSSES
- LOW DYNAMIC LOSSES AS A RESULT OF THE SCHOTTKY BARRIER
- AVALANCHE RATED

DESCRIPTION

Dual center tap Schottky rectifiers suited for switchmode power supply and high frequency DC to DC converters.

Packaged in TO-220AB, ISOWATT220AB and D²PAK, these devices are intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit		
V _{RRM}	Repetitive peak reverse voltage			40	V		
I _{F(RMS)}	RMS forward current			20	A		
I _{F(AV)}	Average forward current	T _c = 135°C $\delta = 0.5$	Per diode Per device	5 10	A		
I _{FSM}	Surge non repetitive forward current	tp = 10 ms Sinusoidal		150	A		
I _{RRM}	Peak repetitive reverse current	tp = 2 μs F = 1kHz square		1	A		
I _{RSR}	Non repetitive peak reverse current	tp = 100 μs square		2	A		
T _{stg}	Storage temperature range			- 65 to + 150	°C		
T _j	Maximum operating junction temperature *			150	°C		
dV/dt	Critical rate of rise of reverse voltage			10000	V/μs		

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$ thermal runaway condition for a diode on its own heatsink

STPS10L40CT/CG/CF

THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB D ² PAK	Per diode Total	3 1.7	$^{\circ}\text{C/W}$
$R_{th(c)}$			Coupling	0.35	
$R_{th(j-c)}$	Junction to case	ISOWATT220AB	Per diode Total	5 3.8	$^{\circ}\text{C/W}$
$R_{th(c)}$			Coupling	2.5	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$$

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I_R *	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			0.2	mA
		$T_j = 100^{\circ}\text{C}$			8	25	mA
V_F *	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 5 \text{ A}$			0.53	V
		$T_j = 125^{\circ}\text{C}$	$I_F = 5 \text{ A}$		0.36	0.46	
		$T_j = 25^{\circ}\text{C}$	$I_F = 10 \text{ A}$			0.67	
		$T_j = 125^{\circ}\text{C}$	$I_F = 10 \text{ A}$		0.49	0.59	

Pulse test : * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation :

$$P = 0.33 \times I_{F(AV)} + 0.026 I_{F}^2(\text{RMS})$$

Fig. 1: Average forward power dissipation versus average forward current (per diode).

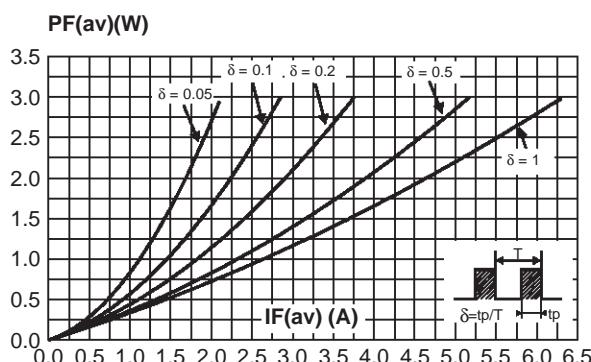


Fig. 2: Average forward current versus ambient temperature ($\delta=0.5$, per diode).

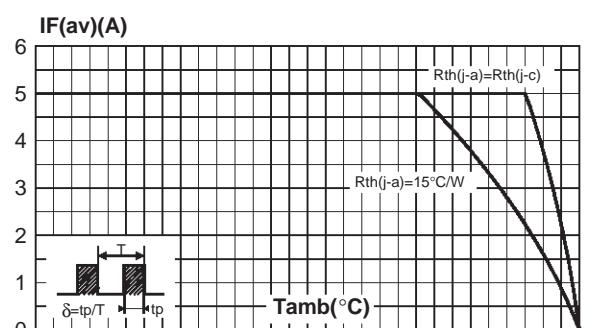


Fig. 3-1: Non repetitive surge peak forward current versus overload duration (maximum values, per diode) (TO-220AB and D²PAK).

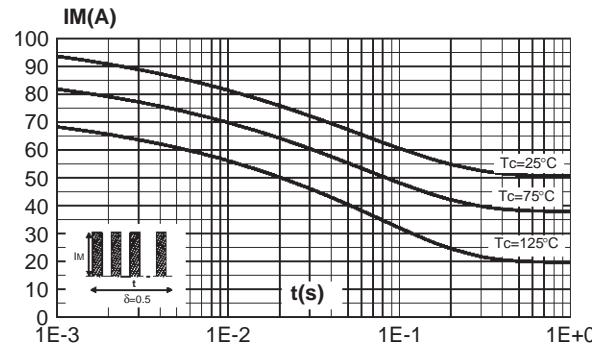


Fig. 4-1: Relative variation of thermal impedance junction to case versus pulse duration. (TO-220AB and D²PAK).

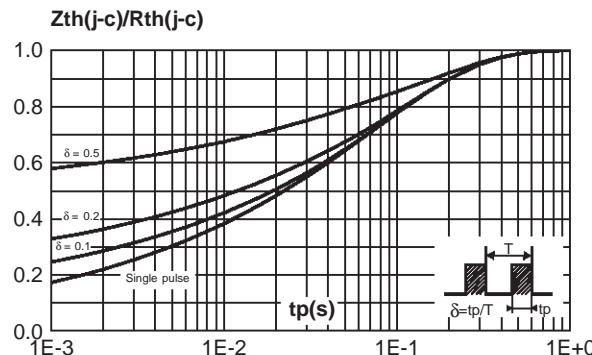


Fig. 5: Reverse leakage current versus reverse voltage applied (typical values, per diode).

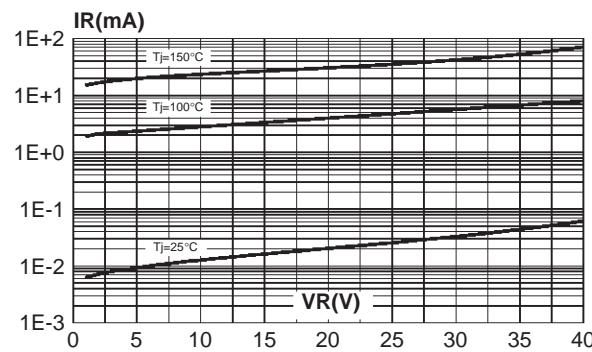


Fig. 3-2: Non repetitive surge peak forward current versus overload duration (maximum values, per diode) (ISOWATT220AB).

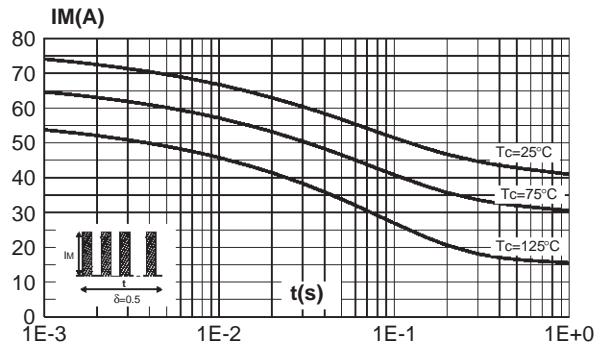


Fig. 4-2: Relative variation of thermal impedance junction to case versus pulse duration. (ISOWATT220AB).

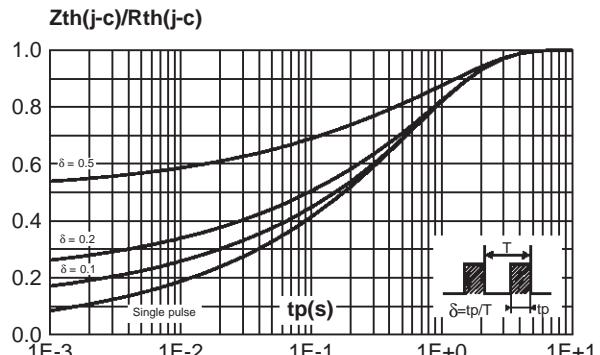
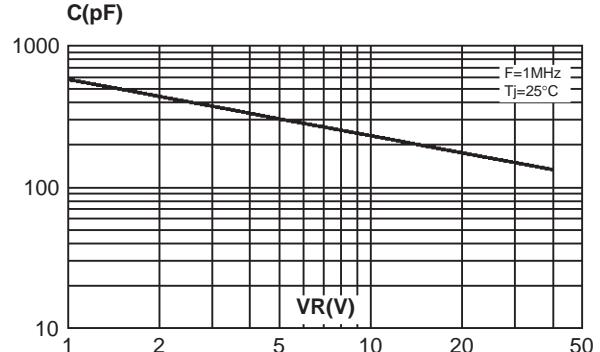


Fig. 6: Junction capacitance versus reverse voltage applied (typical values, per diode).



STPS10L40CT/CG/CF

Fig. 7: Forward voltage drop versus forward current (maximum values, per diode).

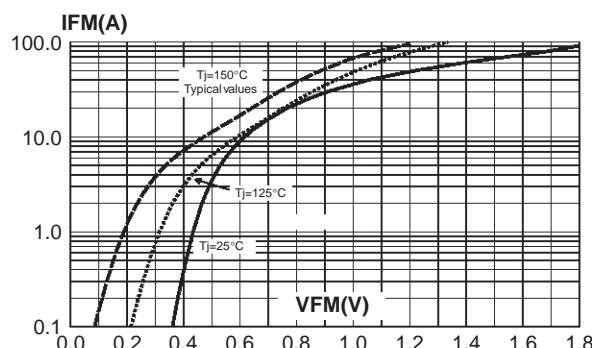
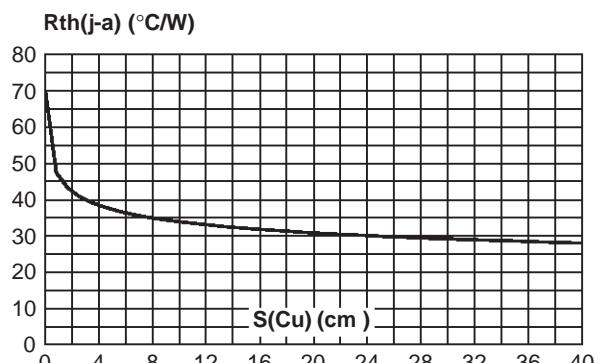
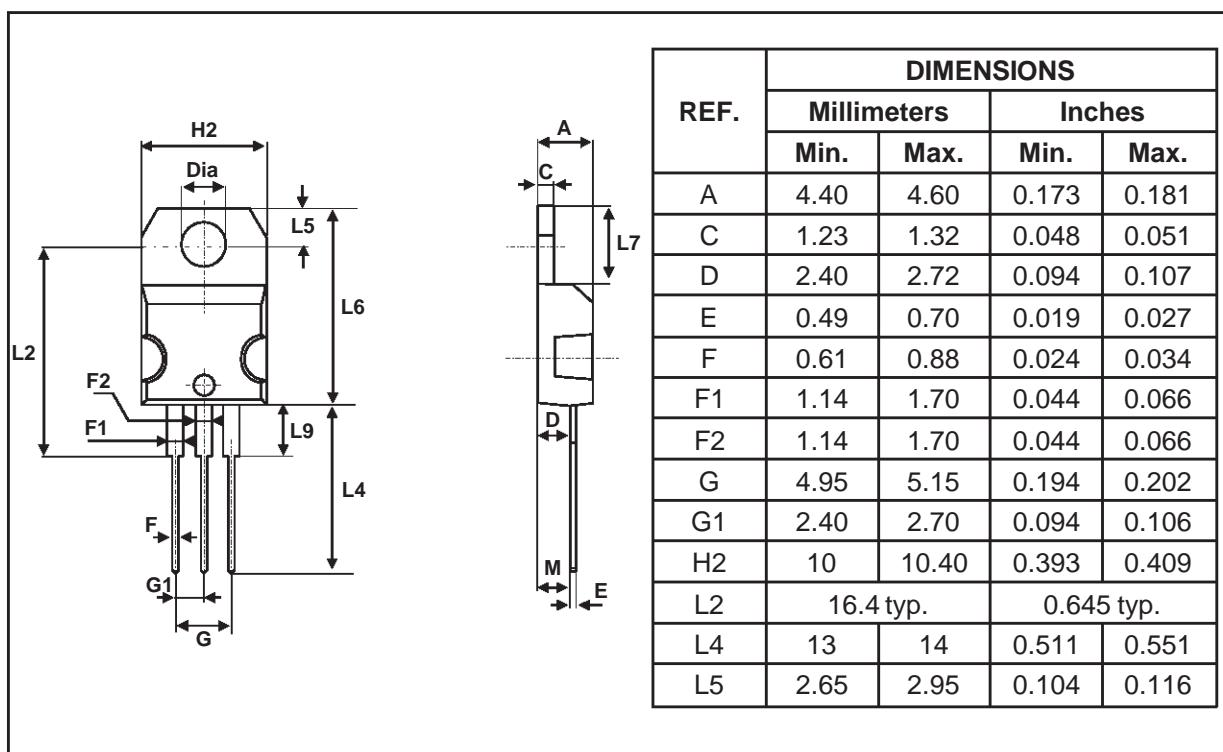


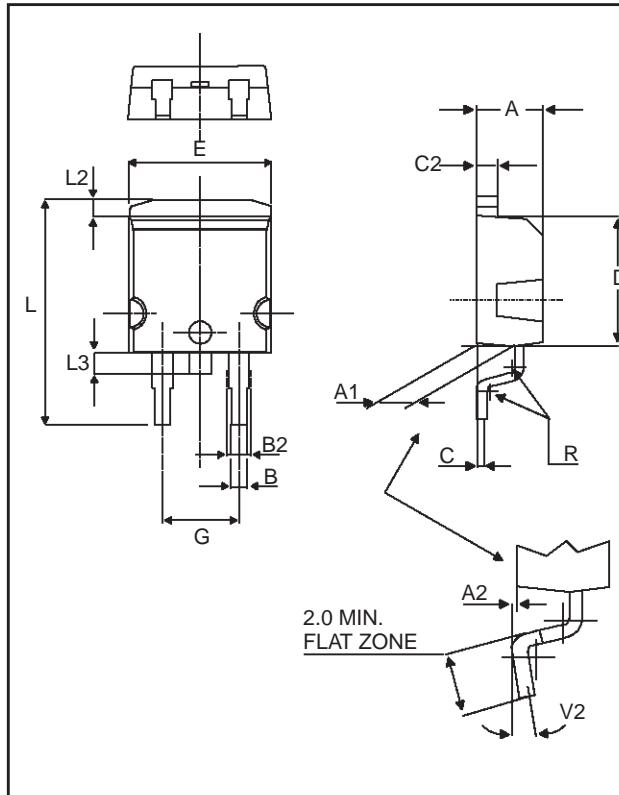
Fig. 8: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35 μ m)(D²PAK).



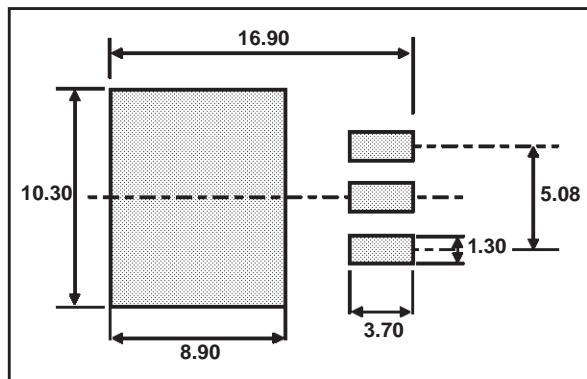
PACKAGE MECHANICAL DATA TO-220AB



- Cooling method : C
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

PACKAGE MECHANICAL DATA
D²PAK


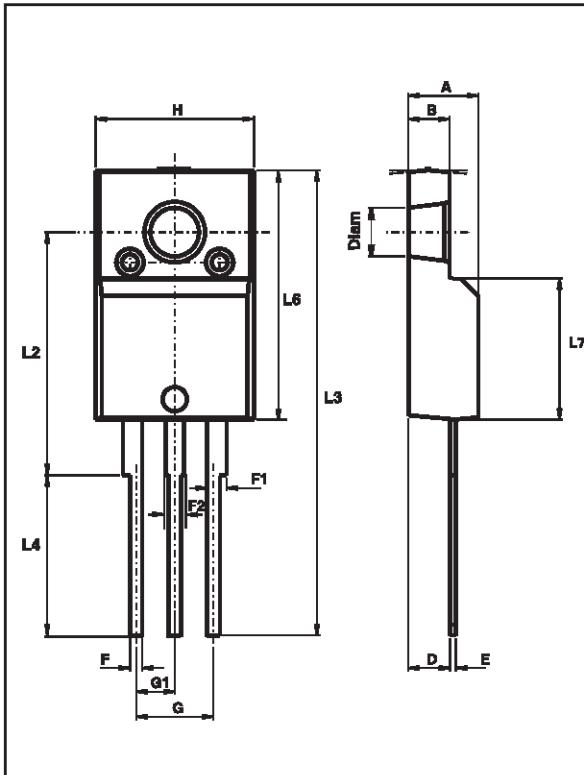
REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.70		0.93	0.027		0.037
B2	1.25	1.40		0.049	0.055	
C	0.45		0.60	0.017		0.024
C2	1.21		1.36	0.047		0.054
D	8.95		9.35	0.352		0.368
E	10.00		10.28	0.393		0.405
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055

FOOT PRINT DIMENSIONS (in millimeters)


- Cooling method: by conduction (method C)

STPS10L40CT/CG/CF

PACKAGE MECHANICAL DATA ISOWATT220AB



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	2.50		2.70	0.098		0.106
D	2.50		2.75	0.098		0.108
E	0.40		0.70	0.016		0.028
F	0.75		1.00	0.030		0.039
F1	1.15		1.70	0.045		0.067
F2	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
G1	2.40		2.70	0.094		0.106
H	10.00		10.40	0.394		0.409
L2		16.00			0.630	
L3	28.60		30.60	1.125		1.205

- Cooling method : C
- Recommended torque value : 0.55m.N
- Maximum torque value : 0.70m.N

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS10L40CT	STPS10L40CT	TO-220AB	2.23g	50	Tube
STPS10L40CG	STPS10L40CG	D ² PAK	1.48g	50	Tube
STPS10L40CG-TR	STPS10L40CG	D ² PAK	1.48g	500	Tape & reel
STPS10L40CF	STPS10L40CF	ISOWATT220AB	2.08g	50	Tube

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.
STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics

© 1998 STMicroelectronics - Printed in Italy - All rights reserved.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - France - Germany - Italy - Japan - Korea - Malaysia - Malta - Mexico - Morocco -
The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.

<http://www.st.com>